



MICROCHIP

QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: NTDO-03NACN832

Date:
May 14, 2026

**Qualification of ATP7 as an additional assembly site for
LX7167CLD-TR and LX7167ACLD-TR catalog part numbers
(CPN) available in 8L WDFN (2x2x0.8mm) package.**



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Package Qualification Report

Purpose: Qualification of ATP7 as an additional assembly site for LX7167CLD-TR and LX7167ACLD-TR catalog part numbers (CPN) available in 8L WDFN (2x2x0.8mm) package.

CCB No.: 7631

Misc.	Assembly site	ATP7
	BD Number	BD-003150 Rev.03
	MP Code (MPC)	U0131QNYCA01
	Part Number (CPN)	LX7167ACLD-TR
	Assembly Shipping Media	Cannister
	Base Quantity Multiple (BQM)	3,000
	Qual ID	R2600041 Rev. A
Lead-Frame	Paddle size	43x71mils
	Material	C194
	DAP Surface Prep	Ring Ag
	Treatment	Rough
	Process	Etch
	Lead-lock	Yes (Half Etch)
	Part Number	101431353
	Lead Plating	Matte Sn
	Strip Size	70x250mm
	Strip Density	2496
Bond Wire	Material	CuPdAu
Die Attach	Part Number	CDF215
	Conductive	Yes
MC	Part Number	G631BQF
PKG	PKG Type	WDFN
	Pin/Ball Count	8
	PKG width/size	2x2x0.8mm



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Package Qualification Report

Manufacturing Information

Assembly Lot No.
ATP7263700001.000
ATP7263700002.000
ATP7263700003.000

Result:

Pass

Fail

Qualification of U0131 mask / LX7167ACLD-TR product / 1.3 mil CuPdAu wire in 8L WDFN 2x2x0.8mm (NYC) package at ATP7 site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards



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Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C		
Required Sample Size	231 units each lot / 3 lots;		
Lot ID	R2600041-1 ATP7263700001.000	R2600041-2 ATP7263700002.000	R2600041-3 ATP7263700003.000
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: ETS300X	25°C		
Results	PASSED		



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Package Qualification Report

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 504 hours		
Required Sample Size	45 units / 1 lot;		
Lot ID	R2600041-1 ATP7263700001.000	R2600041-2 ATP7263700002.000	R2600041-3 ATP7263700003.000
Electrical Results (Fail / Pass)	0/45	0/45	0/45
Electrical Test Tester: ETS300X	25°C		
Results	PASSED		

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-65°C / +150°C Air to Air / 500 Cycles		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2600041-1 ATP7263700001.000	R2600041-2 ATP7263700002.000	R2600041-3 ATP7263700003.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/5	N/A	N/A
WBS (Fail / Pass)	0/5	N/A	N/A
Electrical Test Tester: ETS300X	25°C		
Results	PASSED		



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Package Qualification Report

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130°C / 85%RH / 96 hours / Bias Voltage: 5.0V		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2600041-1 ATP7263700001.000	R2600041-2 ATP7263700002.000	R2600041-3 ATP7263700003.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: ETS300X	25°C		
Results	PASSED		

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130°C / 85%RH / 96 hours		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2600041-1 ATP7263700001.000	R2600041-2 ATP7263700002.000	R2600041-3 ATP7263700003.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: ETS300X	25°C		
Results	PASSED		



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Package Qualification Report

Solderability (0 Hr) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22
Results	PASSED

Physical Dimension (0Hr)

Test Method	JESD22 B100 and B108
Test Criteria	Within package diagram dimension
Required Sample Size	10 units each lot / 3 lots
Result (Fail / Pass)	0/30
Results	PASSED

Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5
Results	PASSED



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Package Qualification Report

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5
Results	PASSED

Wire sweep

Test Method	X-ray
Test Criteria	15%
Required Sample Size	15 wires each lot / 3 lots
Result (Fail / Pass)	0/45
Results	PASSED